

## GBu4001A IST COUPON INFORMATION – Single Level Buried Vias

(With capacitance holes)

This package contains design files for a generic Interconnect Stress Test (IST) Test Coupon containing **Plated Through Hole and Buried Via Technologies** on a 5.0" (126.9mm) X 0.6" (15.2mm) coupon with a total thickness up to .125" (3.2mm) and limited to a minimum of 8 layers. The buried via structure can have multiple layers, located between layers 4 and N-3. This coupon is designed on a small grid, .040" (1mm). The maximum hole/pad size is .015" (.38mm) and pad size is .028" (.71mm) for both power and sense circuits; decreasing these feature sizes will not affect the coupon functionality but increasing these feature sizes may result in shorts or excessively small clearances. Instructions on how to create a custom IST coupon for a specific product are included.

For further information and general inquires on IST technology visit our web site at: [www.pwbcorp.com](http://www.pwbcorp.com)

